



Inventor: Farnworth et al.

Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding Frames

Assignee: Micron Technology, Inc. #3

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5 **INFORMATION DISCLOSURE STATEMENT**

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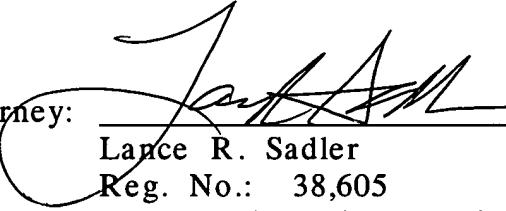
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References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether all the submitted references are prior art.

Respectfully submitted,

Dated: 10/27/98 Attorney: 

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